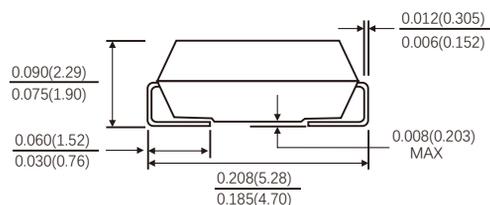
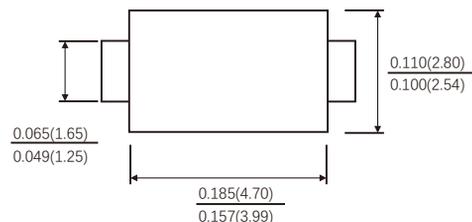


### FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Construction utilizes void-free molded plastic technique
- For surface mounted applications
- Built-in strain relief, ideal for automated placement
- High temperature soldering guaranteed:260°C/10 seconds at terminals
- Component in accordance to RoHS 2015/863/EU



### SMA(DO-214AC)



Dimensions in inches and (millimeters)

### MECHANICAL DATA

- Case: JEDEC SMA(DO-214AC) molded plastic over glass passivated chip
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end

Mounting Position: Any

Weight: 0.002 oz., 0.064 g

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Ratings at 25 C ambient temperature unless otherwise specified ,Single phase ,half wave 60Hz,,resistive or inductive load. For capacitive load, derate by 20%.)

Parameters		Symbols	M1	M2	M3	M4	M5	M6	M7	Units
Maximum Recurrent Peak Reverse Voltage		$V_{RRM}$	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage		$V_{RMS}$	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage		$V_{DC}$	50	100	200	400	600	800	1000	Volts
Maximum average Forward Rectified Current		$I_{AV}$	1.0							Amp
Peak Forward Surge Current (8.3ms half sine-wave superimposed on rated load (JEDEC method)		$I_{FSM}$	30							Amps
Maximum Instantaneous Forward Voltage at 1.0 A (Note 3)		$V_F$	1.1							Volts
Maximum Reverse current at rated DC Blocking Voltage	$T_J=25^{\circ}C$	$I_R$	5.0							$\mu A$
	$T_J=125^{\circ}C$		100							
Typical Thermal resistance (Note 2)		$R_{thJA}$	75							$^{\circ}C/W$
		$R_{thJL}$	30							
ypical Junction Capacitance (Note 1)		$C_j$	12							pF
Operating and Storage temperature Range		$T_J$	-55 to+150							$^{\circ}C$
		$T_{STG}$								

Note: 1.Measured at 1MHz and applied reverse voltage of 4.0V DC

2.Thermal resistance from junction to ambient and from junction to lead , Mounted on P.C.B. With 0.2×0.2"(5.0×5.0mm)copper pad areas.

3. Short duration pulse test used to minimize self-heating effect

FIG.1-FORWARD CURRENT DERATING CURVE

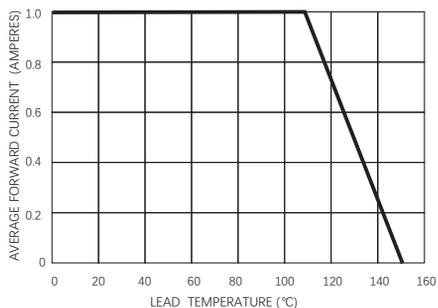


FIG.2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

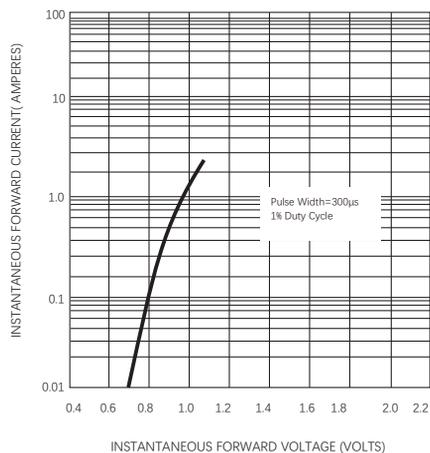


FIG.3-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

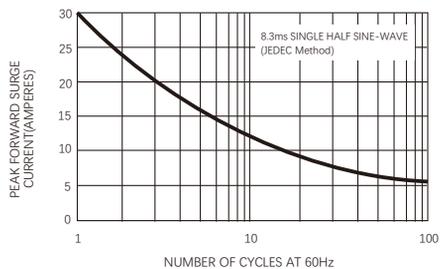


FIG.4-TYPICAL REVERSE CHARACTERISTICS

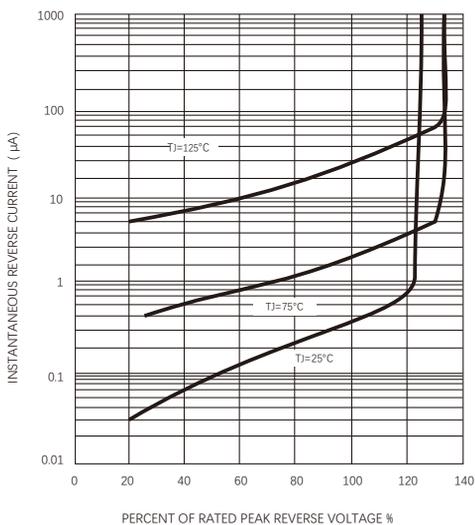
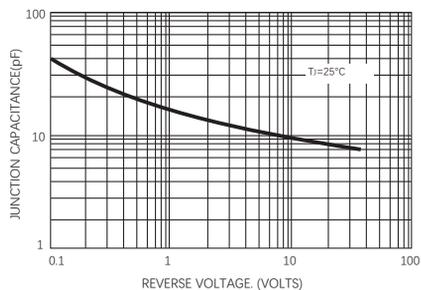


FIG.5-TYPICAL JUNCTION CAPACITANCE



## Friendship Reminder

- JiNan JingHeng (hereinafter referred to as JH) reserves the right to make changes to this document and its products and specifications at anytime without notice.
- Customers should obtain and confirm the latest product information and specifications before final design, purchase or use.
- JH makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does JH assume any liability for application assistance or customer product design.
- JH does not warrant or accept any liability with products which are purchased or used for any unintended or unauthorized application.
- No license is granted by implication or otherwise under any intellectual property rights of JH.
- JH's products are not authorized for use as critical components in life support devices or systems without express written approval of JH.